

High frequency DC/DC converters for future pixel detectors

Verbundmeeting Heidelberg

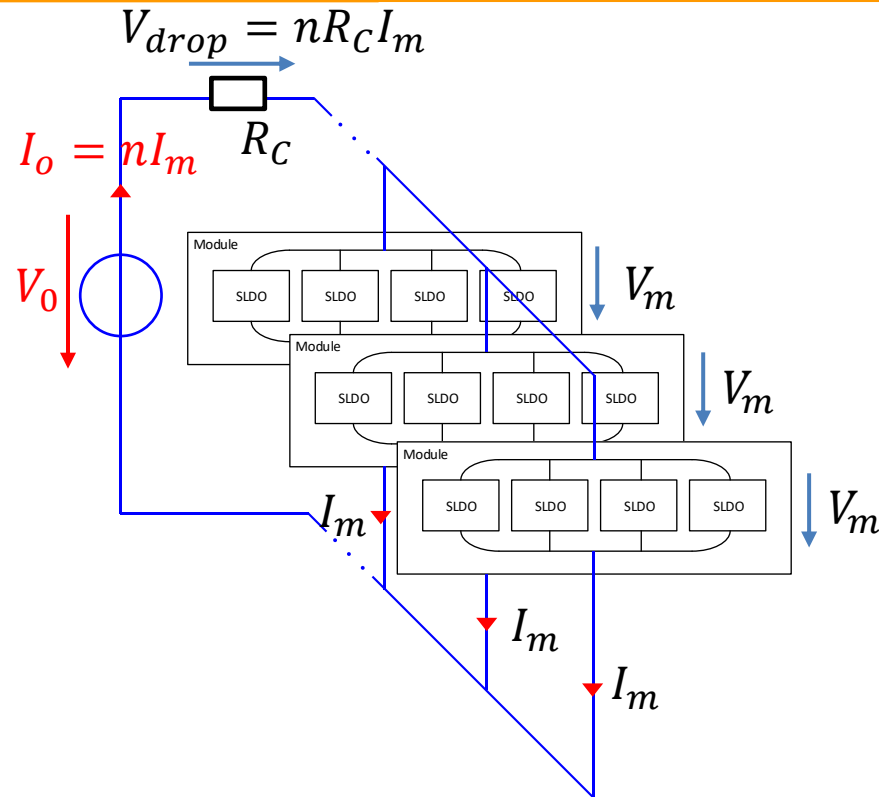
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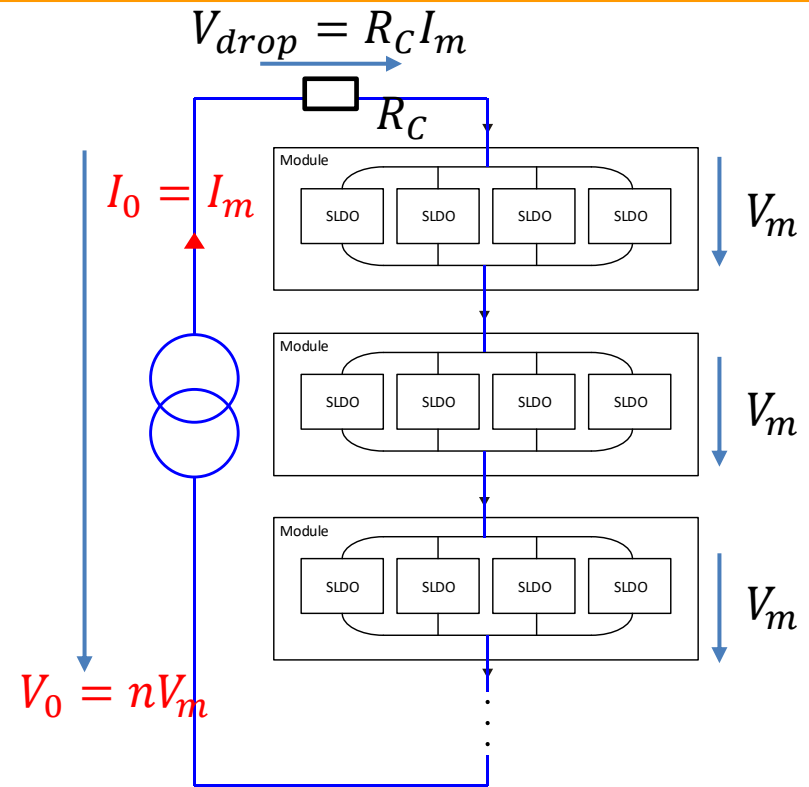
- Future pixel detectors aim for higher luminosity
 - For the upcoming phase II upgrade of the ATLAS and CMS pixel detectors, an increased number of pixels is targeted
 - The increased number of pixels leads to a higher power consumption of the overall detector
 - At constant module voltage a higher supply current leads to higher I^2R losses
 - Target: Reduction of supply current to achieve a good overall efficiency
- High interest for new innovative powering concepts

Parallel Powering vs. Serial Powering



- Modules are connected in parallel and powered by a constant voltage source
- Total supply current scales with the number of modules

$$\eta = \frac{1}{1 + n \frac{R_C I_m}{V_m}}$$

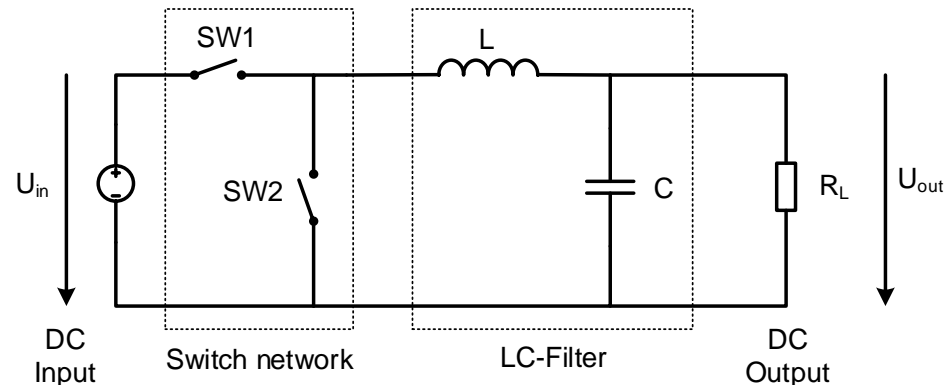


- Modules are connected in series chain and powered by a constant current source
- Total supply current is defined by maximum load current of a single module

$$\eta = \frac{1}{1 + \frac{R_C I_m}{nV_m}}$$

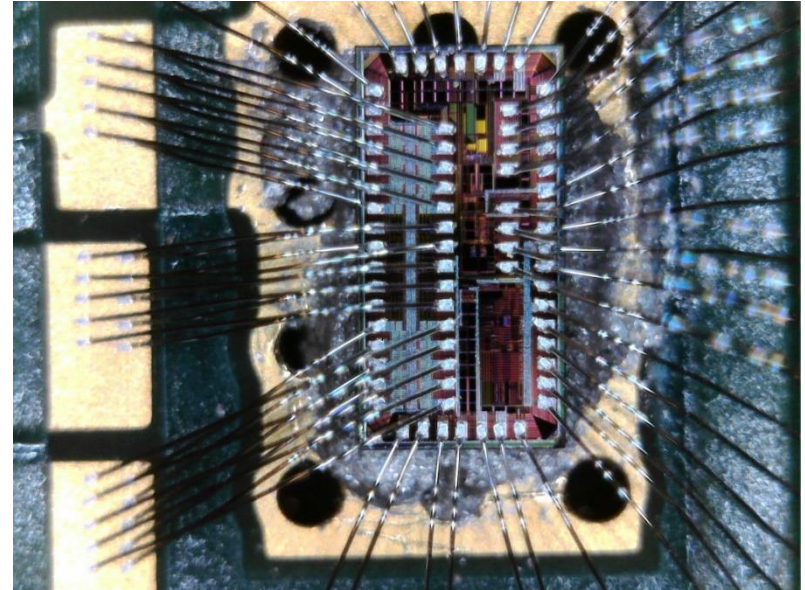
DC/DC converter requirements & challenges

- A **total ionizing dose of up to 1 Grad** should be tolerated
 - Low voltage core transistors of a 65nm TSMC CMOS technology
 - A **voltage conversion factor of 4** is targeted (input voltage is 4 times higher than module voltage)
 - For the realization of short module chains (3D sensor modules)
- **Device Stacking necessary**
- **Space requirements:**
 - High magnetic field inside the detector: **Only bulky air coils** can be used for the inductor
- To meet the space requirements the inductance has to be reduced (reduced volume)
- Operation at **high switching frequencies (Multi MHz)**



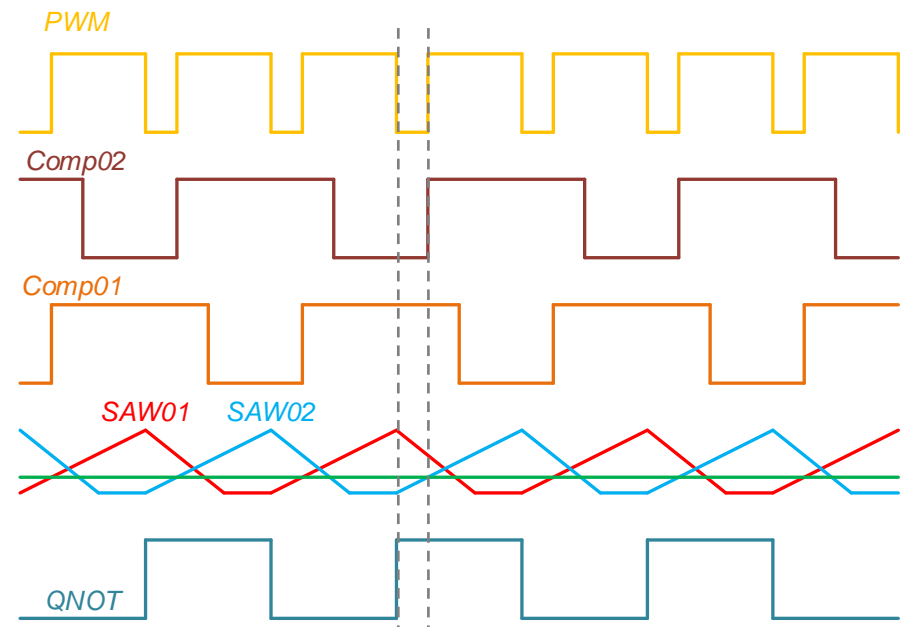
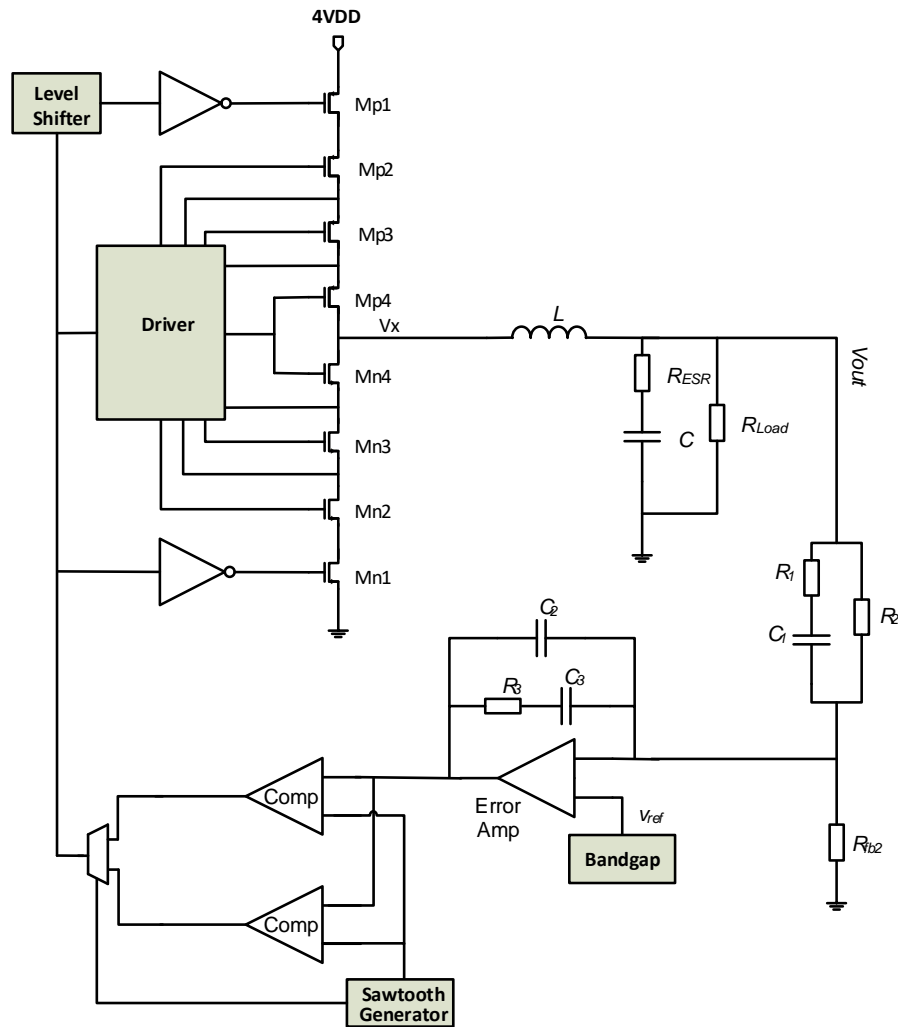
A high frequency DC/DC-converter (prototype)

- TSMC 65nm
 - Low voltage core transistors (nominal voltage = 1.2V)
- Area: 1 x 2mm
- Switching frequency: 100MHz
- Input Voltage: 4.8V
- Output voltage: 1.2V
- Voltage conversion factor: 4
- Max. load current: 1A
- Passive components (off Chip)
 - Inductor $L = 22\text{nH}$
 - Capacitor $C = 100\text{nF}$

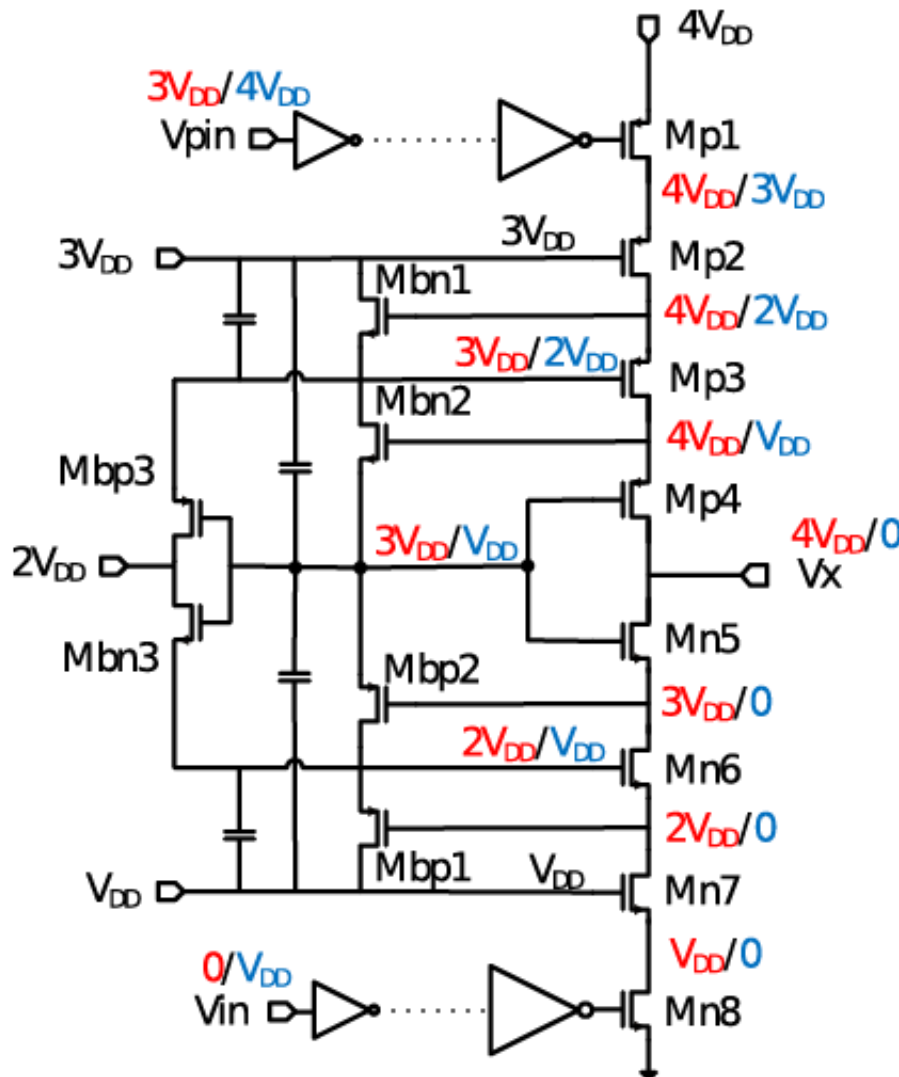


Prototype overview

- Voltage mode PWM control

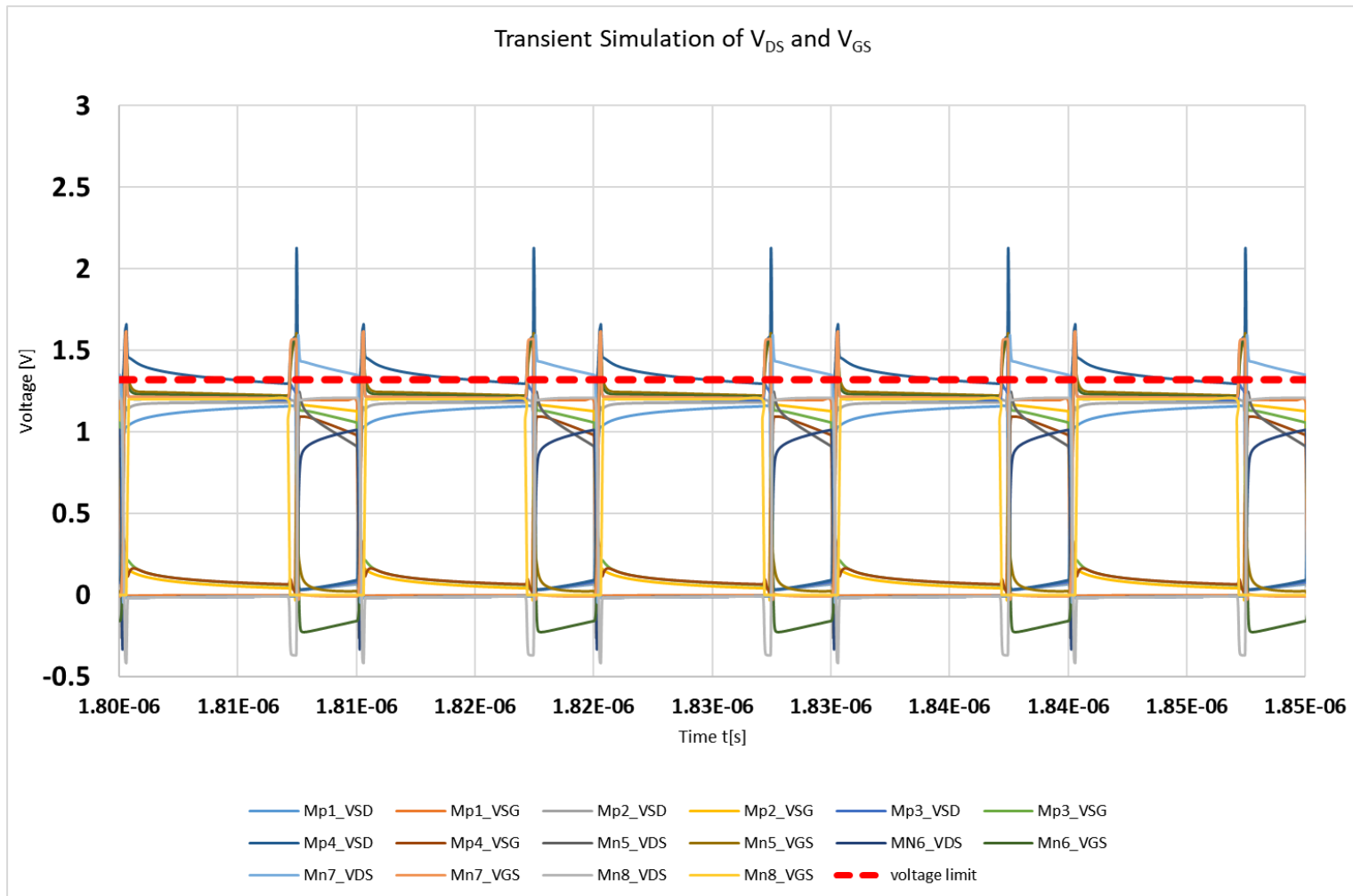


Device stacking of the switching stage

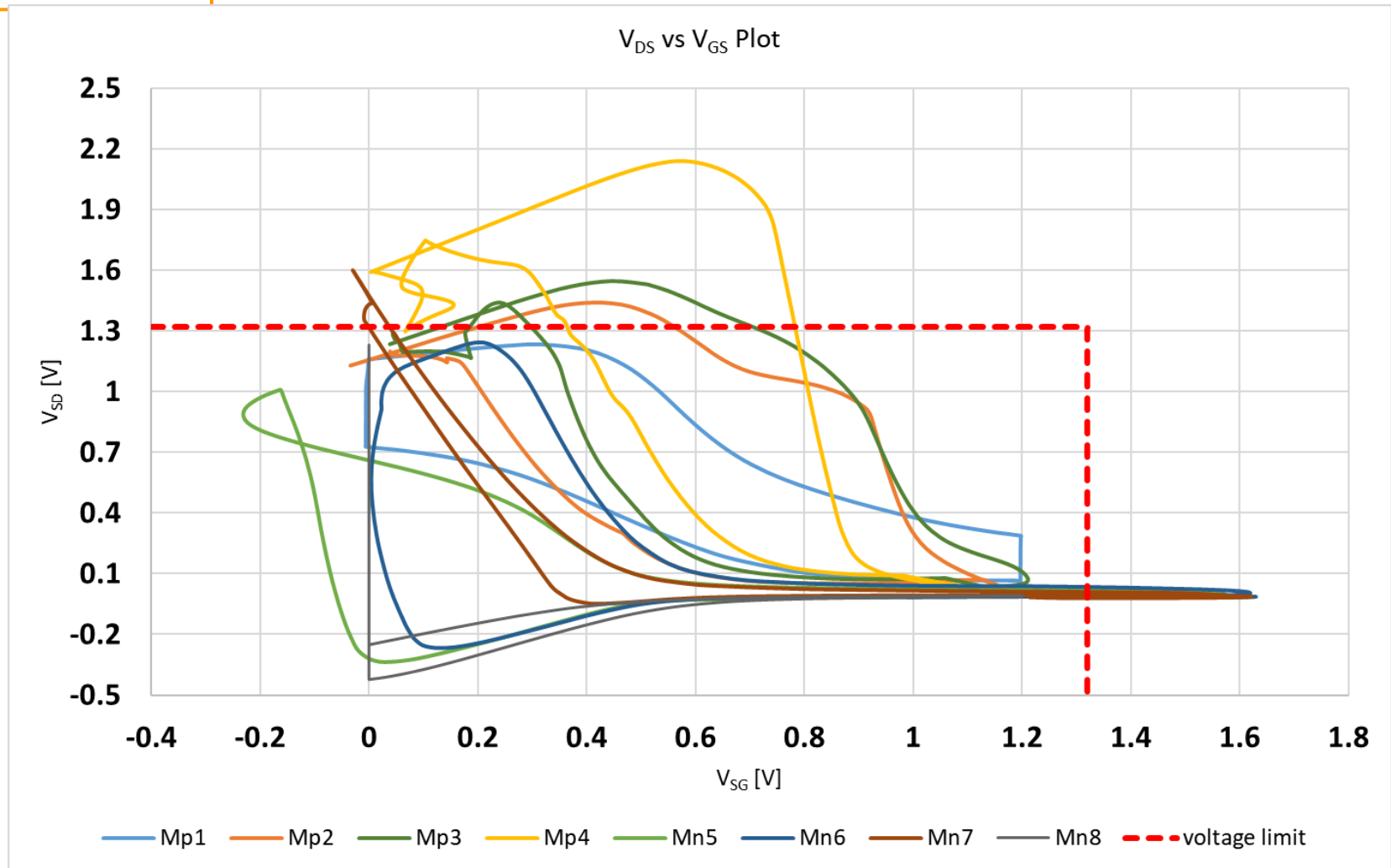


- 4 stacked PMOS and NMOS power devices
- Circuit switches between High state (red) and Low state (blue)
 - Control signals of Mp1 & Mn8 determine the state of the circuit
- Biasing network ensures safe operation of stacked transistors
 - Biasing network monitors drain potential of cascode devices and applies the required gate voltage
 - Ensures that cascode devices remain within their voltage limits
- Benefit: **only two control signals necessary**
- Drawback: **voltage overshoots during switching moment (hot carrier effect)**

Voltage overshoot during switching moment



Drain Source vs. Gate Source voltage of stacked devices



Improved Concept: J. Kampkoetter, M. Karagounis: Design and characterization of a cascode switching stage for high frequency radiation hardened DC/DC converters for the supply of future pixel detectors; Twepp 2022

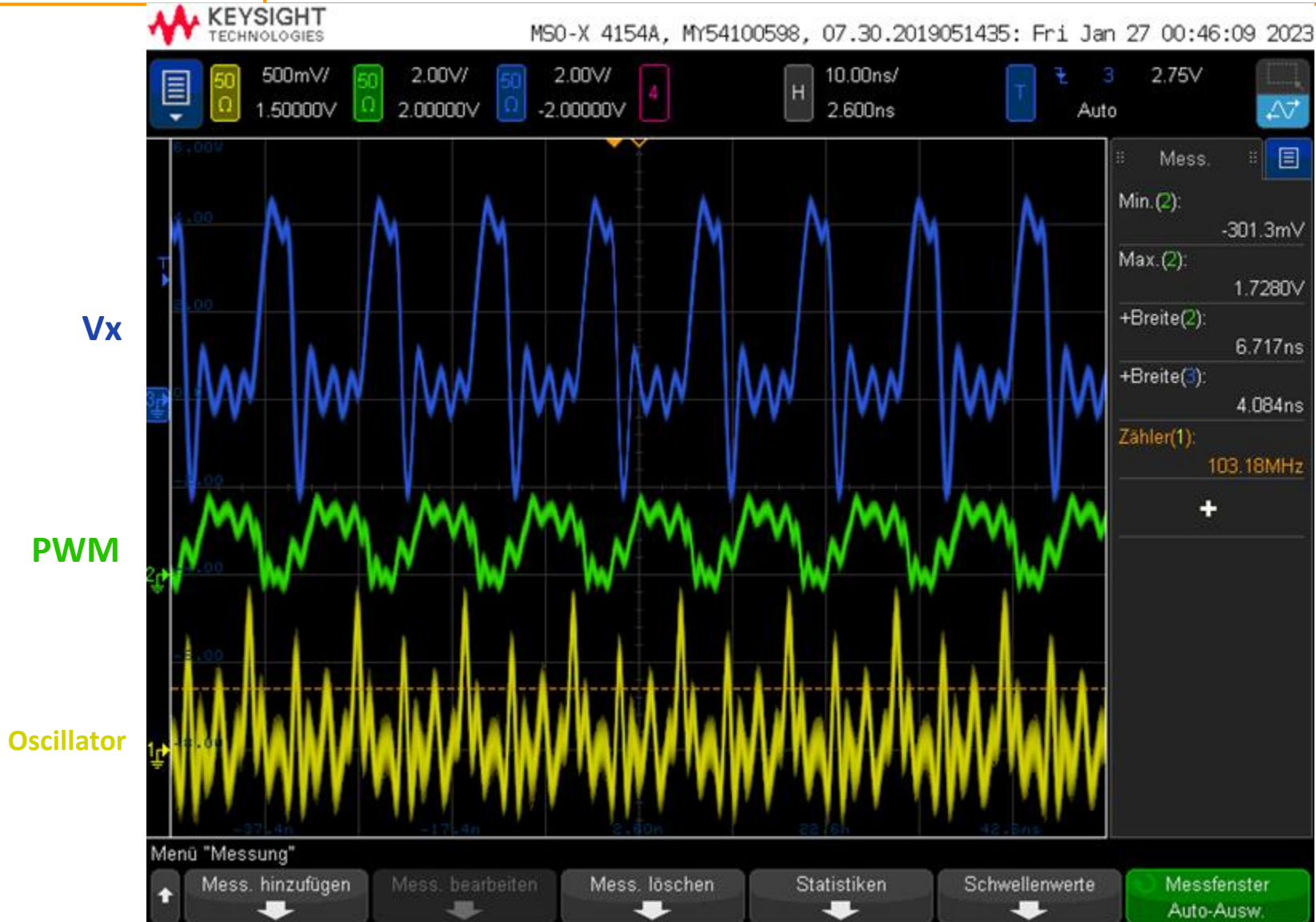
MEASUREMENT RESULTS

Sawtooth Oscillator (100MHz)



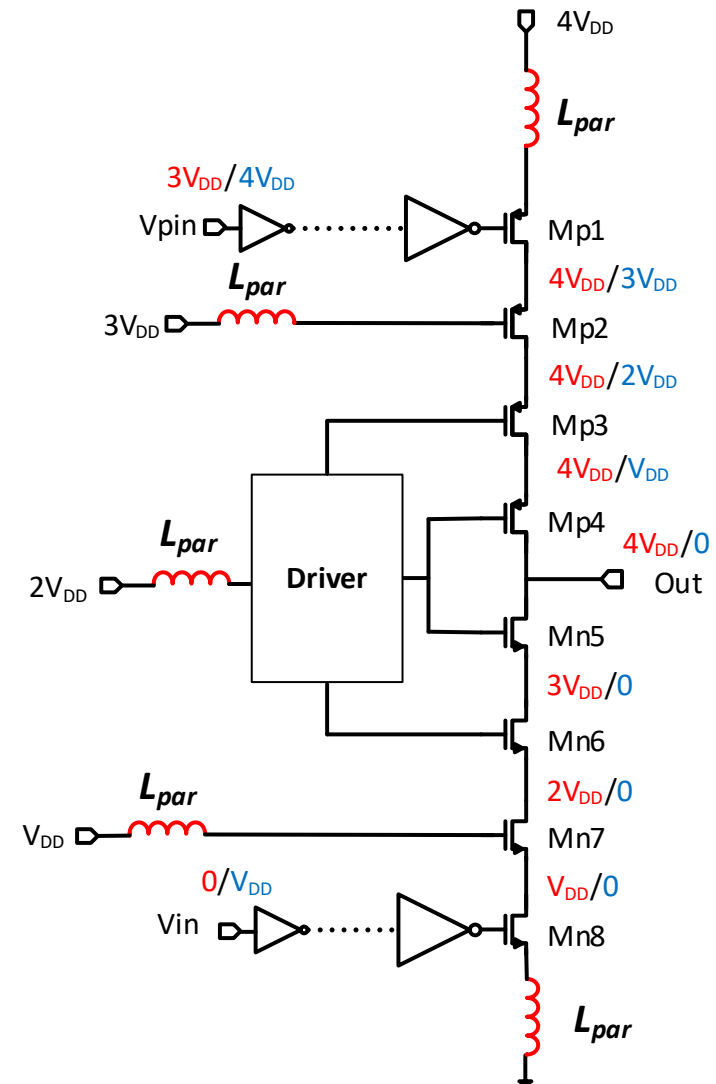
- Pulse signal becomes active as soon as ramp signal reaches its upper limit
 - Method for determining the switching frequency

Closed Loop Measurement (load current 100mA)



Parasitic effects of bond wires

- Fast switching of Mp1 and Mn8 (100 – 300ps)
 - To enable high frequencies and small duty cycles
 - Large power devices to handle high currents
- High current flow during switching action across bond wires
 - High di/dt
 - $\Delta v = L_{par} \frac{di}{dt}$
 - Leads to increase or decrease of the supply voltages and ground bouncing
- Voltage limits of transistors can be exceeded!
- Incorrect switching behaviour!
 - Failure of whole system!
- To avoid unwanted effects, it is necessary to take the influence of parasitic inductivities into account!!!



Measures to reduce parasitic inductances

- Adopted measures:
 - Several bond wires in parallel for critical current paths
 - Reduces total inductivity
 - Bond wires as short as possible
 - On Chip Decoupling caps for supply connectors (range of 100 – 200pF)
 - OFF-Chip Decoupling close to the chip
- Recent measurements show that the measures are not sufficient for the entire load range!
- Potential measures for future prototypes:
 - Larger on chip decoupling caps (range of 1...4nF)
 - Drawback: Consume a large area of the chip
 - Bump Bonding
 - Reduces influence of parasitic effects by a factor of 10 compared to the use of bonding wires

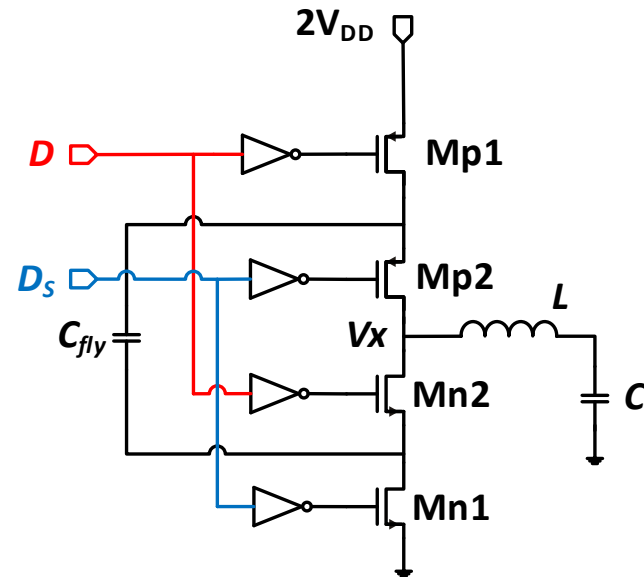
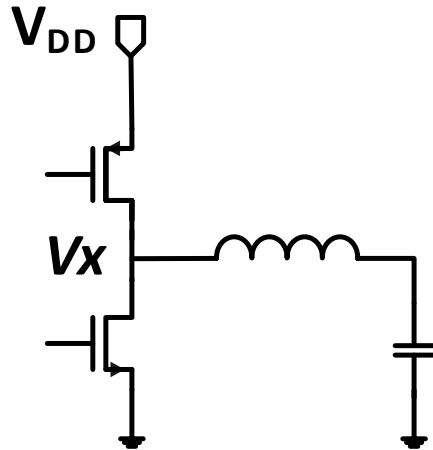
Future plans

HYBRID CONVERTERS

Hybrid Converter

- Combine positive properties of capacitive and inductive switching converter
- **Goal:** Better utilization of passive components (reduction of their volume)
- Compared to conventional buck topologies hybrid converter reduce the size of magnetic components
 - Decreasing the volt second (V_s) balance product
- Compared to pure switched capacitor topologies:
 - Reduced charge sharing losses
- Wide range of different topologies: Series Parallel, N-Level Buck, Dixon ...
 - Many ways to configure switches and passive components
- Multimode operation
 - Resonant (soft switching, reduces switching losses)
 - Inductive

2-Level Buck Converter (conventional) vs. 3-Level Buck Converter



- Additional Flying Capacitor
- Higher blocking voltage ($2V_{DD}$)
- Up to $\frac{1}{4}$ lower current ripple at the inductor (smaller voltage drop)
 - Lower inductance or lower frequency
- 4 switching phases instead of 2: Effectively uses twice the frequency
 - Lower output voltage ripple

→ High potential for future applications

**Thank you for your
attention!**